## A. Interconnect & Package 분과

**2019년 2월 14일(목), 11:00-12:30**
**Room E (스카이홀, 2층)**

### [TE2-A] Interconnect & Package

**좌장:** 이후정 교수(성균관대학교), 최광성 박사(ETRI)

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| **TE2-A-1**<br>**11:00-11:30** | **[초청]**<br>**Studies on Electronic Materials in Recent Advanced Packaging : Package Level EMI Shielding Pastes and Core/Shell Fillers**<br>Seyoung Jeong,[1] Kisu Joo[1], Taeryong Kim[2], Kyu Jae Lee[1], and Jung Woo Hwang[1]<br>*[1]Ntrium Incorporation, [2]Department of Materials Science and Engineering, Seoul National University* |
| **TE2-A-2**<br>**11:30-11:45** | **Tungsten Thin Film Grown by Plasma-Enhanced Atomic Layer Deposition Using Fluorine Free Precursor**<br>Hwi Yoon[1], Seunggi Seo[1], Yujin Lee[1], Bonggeun Shong[2], Kyu-Hyun Yeom[3], Jungwun Hwang[3], Jang Hyeon Seok[3], Jung Woo Park[3], and Hyungjun Kim[1]<br>*[1]School of Electrical and Electronic Engineering, Yonsei University, [2]Department of Chemical Engineering, Hongik University, [3]Hansol Chemical* |
| **TE2-A-3**<br>**11:45-12:00** | **피치 변화에 따른 테스트 프로브 핀의 등가회로 영향 분석**<br>Cheolhong Park, Moonjung Kim<br>*Department of Electrical Electronic and Control Engineering, Kongju National University* |
| **TE2-A-4**<br>**12:00-12:15** | **Thermal Stability and Endurance of Nitrogen-Doped SiTe Ovonic Threshold Switch**<br>Jeongun Choe[1,2], Deok-Jin Jeon[1,2], Jihye Lee[1,2], JaeHyun Kang[1,2], and Jong-Souk Yeo[1,2]<br>*[1]School of Integrated Technology, Yonsei University,*<br>*[2]Yonsei Institute of Convergence Technology, Yonsei University* |
| **TE2-A-5**<br>**12:15-12:30** | **Screening of Reducing Agent for Atomic Layer Deposition of Tungsten Using $WCl_5$: Density Functional Theory Study**<br>Romel Hidayat[1], 김성윤[1], 김수현[2], 이원준[1]<br>*[1]세종대학교 나노신소재공학과, [2]영남대학교 신소재공학과* |